

MOS FIELD EFFECT TRANSISTOR
2SK2510

SWITCHING
 N-CHANNEL POWER MOS FET
 INDUSTRIAL USE

DESCRIPTION

The 2SK2510 is N-Channel MOS Field Effect Transistor designed for high current switching applications.

FEATURES

- Super Low On-Resistance
 $R_{DS(on)1} = 20 \text{ m}\Omega$ ($V_{GS} = 10 \text{ V}$, $I_D = 20 \text{ A}$)
 $R_{DS(on)2} = 30 \text{ m}\Omega$ ($V_{GS} = 4 \text{ V}$, $I_D = 20 \text{ A}$)
- Low C_{iss} $C_{iss} = 1\ 600 \text{ pF TYP.}$
- Built-in G-S Protection Diode

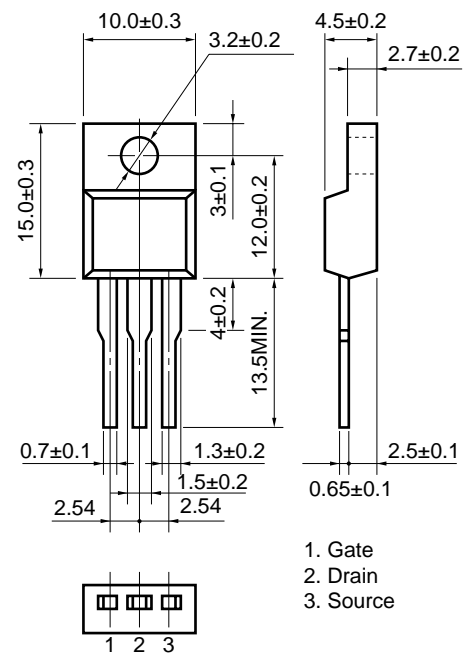
ABSOLUTE MAXIMUM RATINGS ($T_A = 25 \text{ }^\circ\text{C}$)

Drain to Source Voltage	V_{bss}	60	V
Gate to Source Voltage	V_{gss}	± 20	V
Drain Current (DC)	$I_{D(DC)}$	± 40	A
Drain Current (pulse)*	$I_{D(pulse)}$	± 160	A
Total Power Dissipation ($T_c = 25 \text{ }^\circ\text{C}$)	P_{T1}	35	W
Total Power Dissipation ($T_A = 25 \text{ }^\circ\text{C}$)	P_{T2}	2.0	W
Channel Temperature	T_{ch}	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

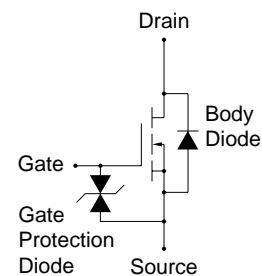
* $PW \leq 10 \text{ }\mu\text{s}$, Duty Cycle $\leq 1 \%$

The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device is actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

PACKAGE DIMENSIONS
 (in millimeter)



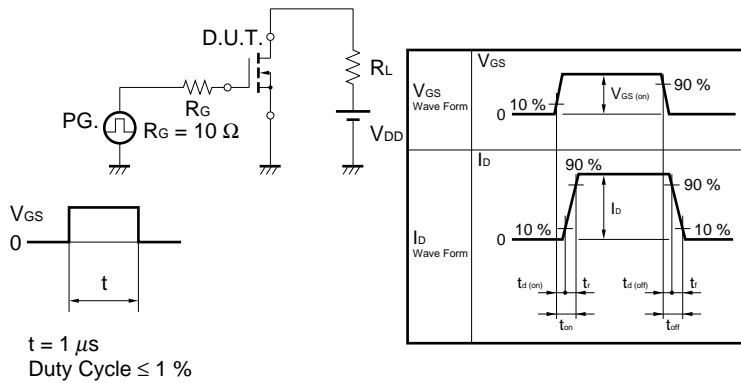
MP-45F (ISOLATED TO-220)



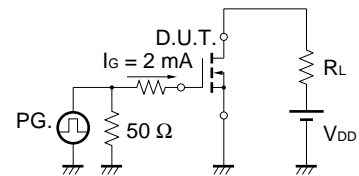
ELECTRICAL CHARACTERISTICS (T_A = 25 °C)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Drain to Source On-Resistance	R _{DS (on)1}		16	20	mΩ	V _{GS} = 10 V, I _D = 20 A
Drain to Source On-Resistance	R _{DS (on)2}		24	30	mΩ	V _{GS} = 4 V, I _D = 20 A
Gate to Source Cutoff Voltage	V _{GS (off)}	1.0	1.5	2.0	V	V _{DS} = 10 V, I _D = 1 mA
Forward Transfer Admittance	y _{fs}	13			S	V _{DS} = 10 V, I _D = 20 A
Drain Leakage Current	I _{DSS}			10	μA	V _{DS} = V _{DSS} , V _{GS} = 0
Gate to Source Leakage Current	I _{GSS}			±10	μA	V _{GS} = ±20 V, V _{DS} = 0
Input Capacitance	C _{ISS}		1 600		pF	V _{DS} = 10 V
Output Capacitance	C _{OSS}		780		pF	V _{GS} = 0
Reverse Transfer Capacitance	C _{RSS}		350		pF	f = 1 MHz
Turn-On Delay Time	t _{d (on)}		35		ns	I _D = 20 A
Rise Time	t _r		380		ns	V _{GS (on)} = 10 V
Turn-Off Delay Time	t _{d (off)}		220		ns	V _{DD} = 30 V
Fall Time	t _f		300		ns	R _G = 10 Ω
Total Gate Charge	Q _G		69		nC	I _D = 40 A
Gate to Source Charge	Q _{GS}		5.0		nC	V _{DD} = 48 V
Gate to Drain Charge	Q _{GD}		26		nC	V _{GS} = 10 V
Body Diode Forward Voltage	V _{F (S-D)}		1.0		V	I _F = 40 A, V _{GS} = 0
Reverse Recovery Time	t _{rr}		72		ns	I _F = 40 A, V _{GS} = 0
Reverse Recovery Charge	Q _{rr}		130		nC	di/dt = 100 A/μs

Test Circuit 1 Switching Time



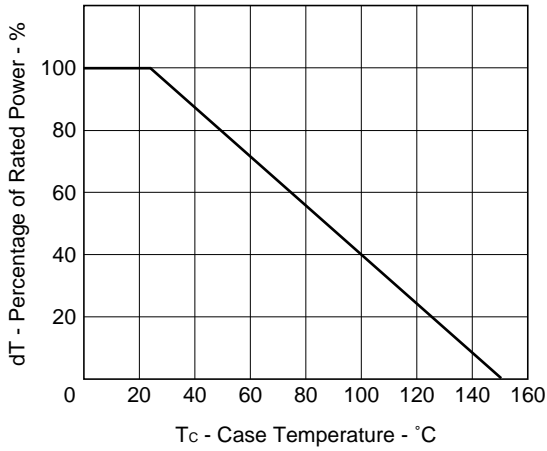
Test Circuit 2 Gate Charge



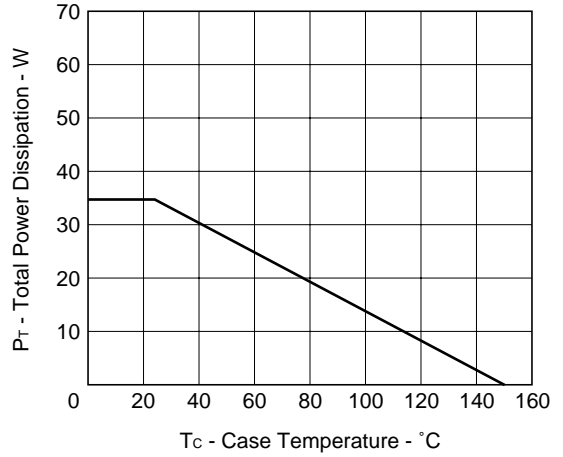
The application circuits and their parameters are for references only and are not intended for use in actual design-in's.

TYPICAL CHARACTERISTICS (T_A = 25 °C)

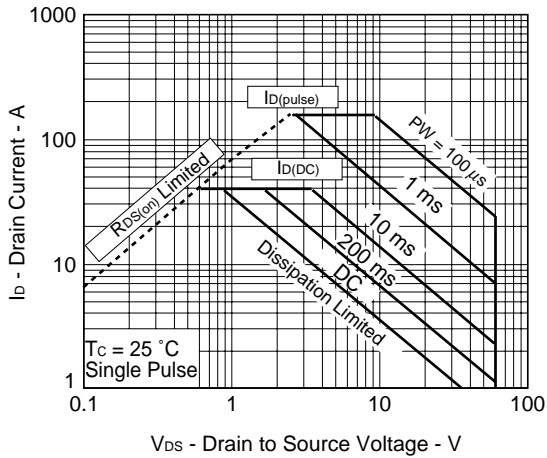
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



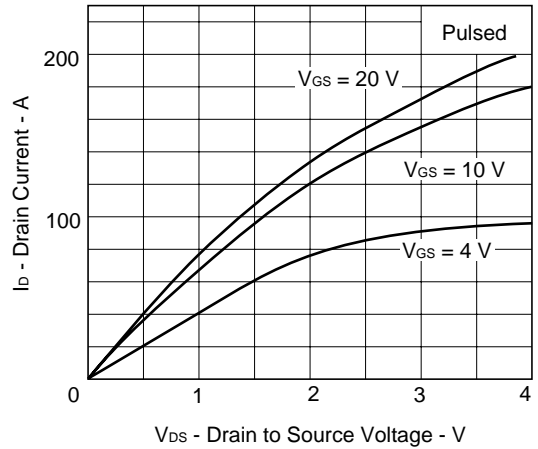
TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



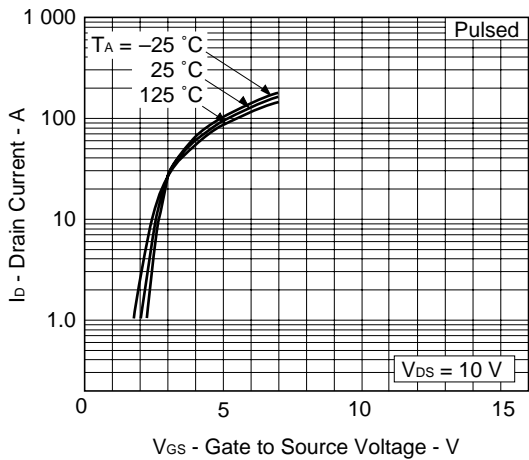
FORWARD BIAS SAFE OPERATING AREA



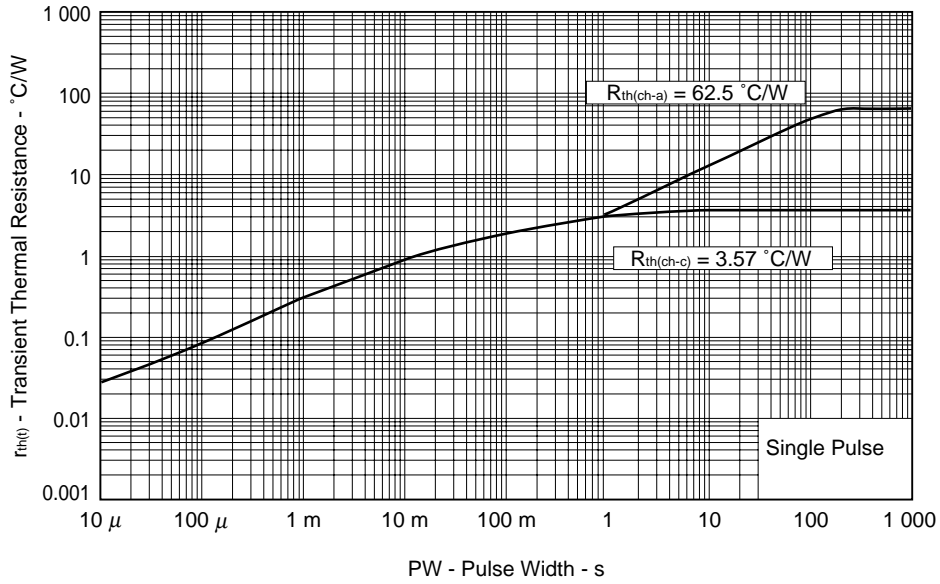
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



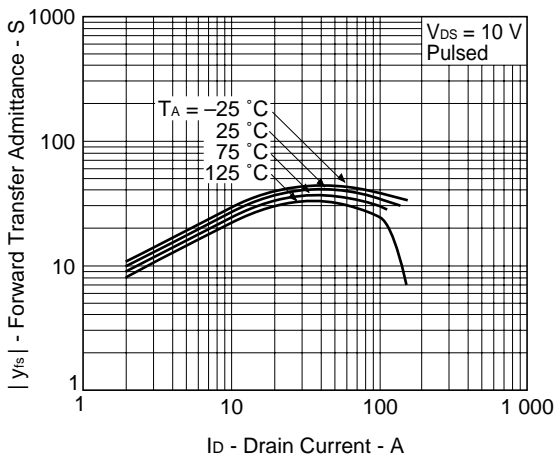
FORWARD TRANSFER CHARACTERISTICS



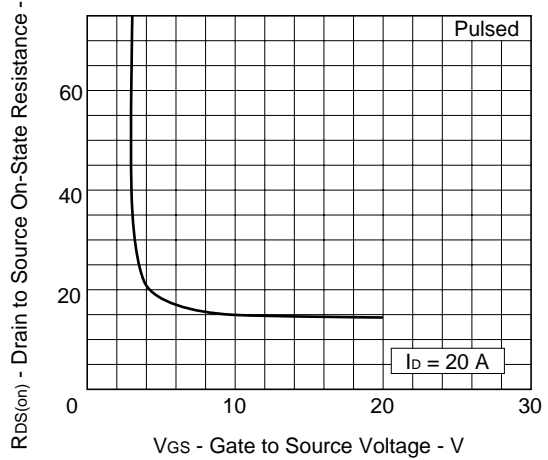
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



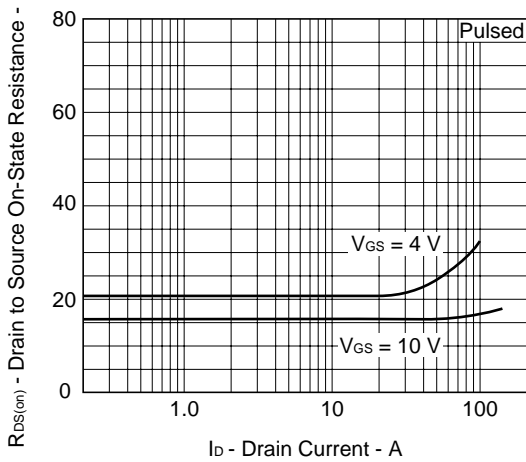
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



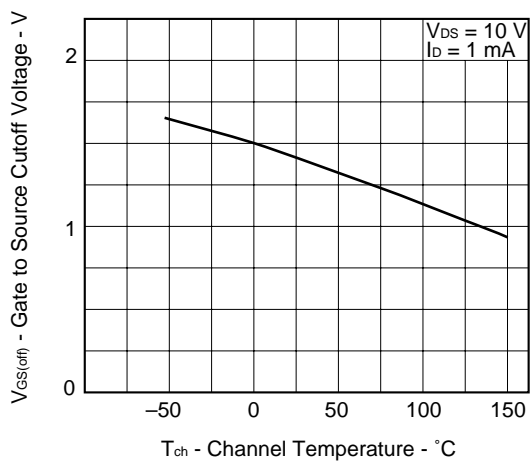
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

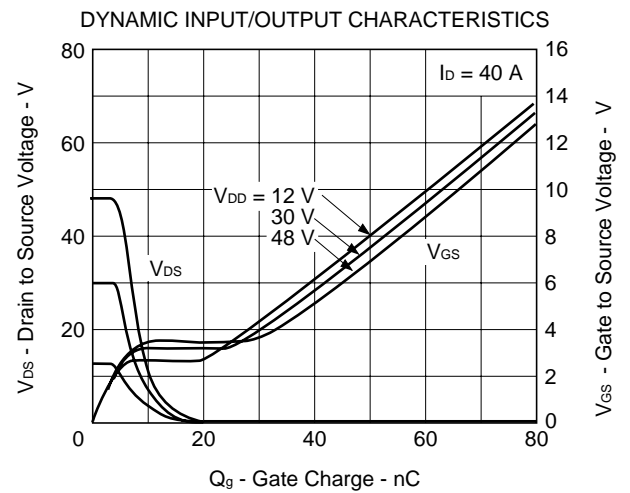
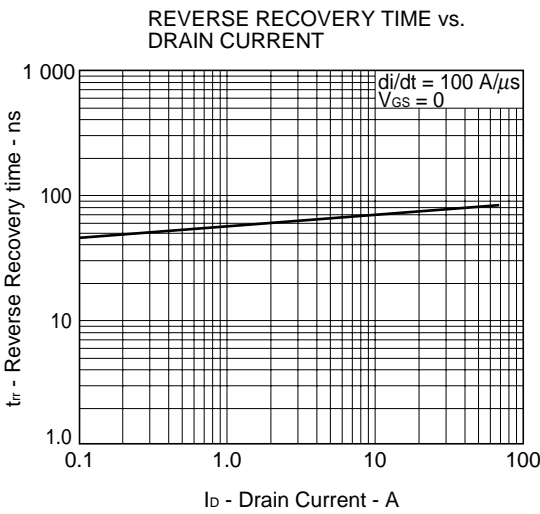
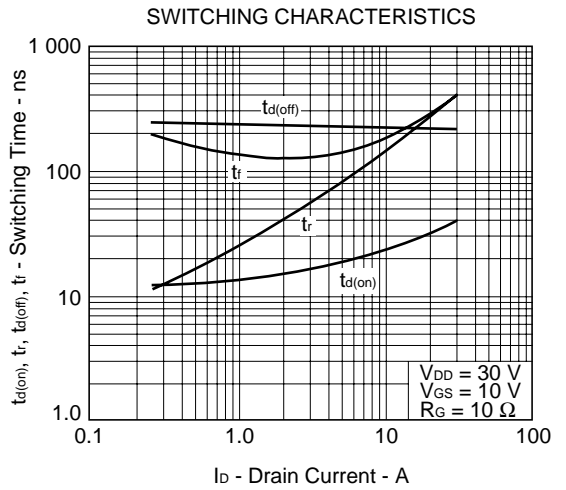
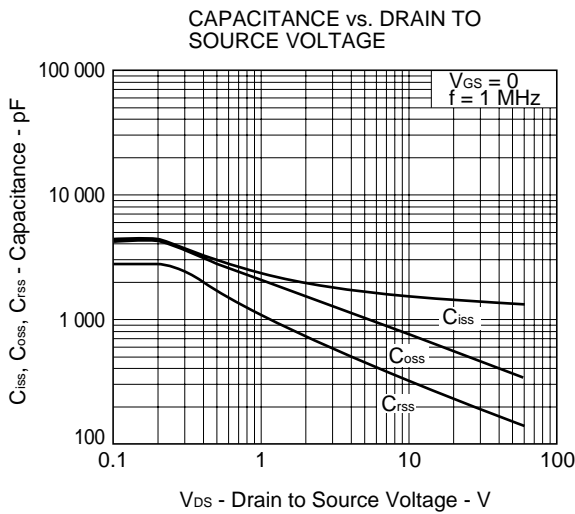
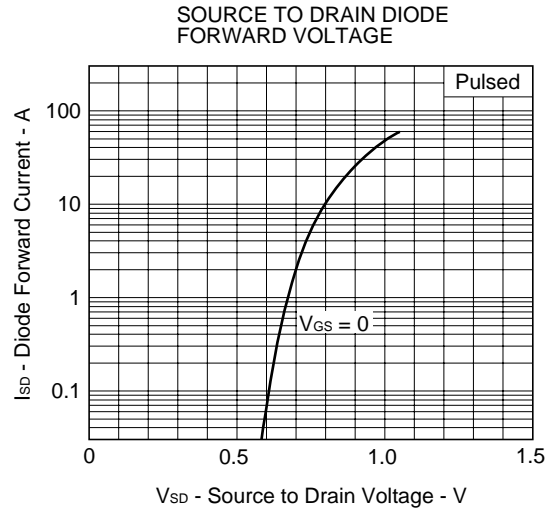
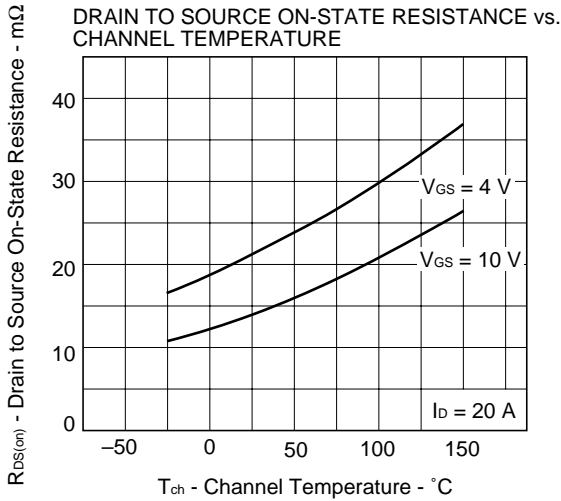


DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



GATE TO SOURCE CUTOFF VOLTAGE vs. CHANNEL TEMPERATURE





REFERENCE

Document Name	Document No.
NEC semiconductor device reliability/quality control system.	TEI-1202
Quality grade on NEC semiconductor devices.	IEI-1209
Semiconductor device mounting technology manual.	IEI-1207
Semiconductor device package manual.	IEI-1213
Guide to quality assurance for semiconductor devices.	MEI-1202
Semiconductor selection guide.	MF-1134
Power MOS FET features and application switching power supply.	TEA-1034
Application circuits using Power MOS FET.	TEA-1035
Safe operating area of Power MOS FET.	TEA-1037

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Anti-radioactive design is not implemented in this product.